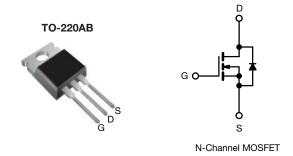


## **Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	100				
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V 0.54				
Q <sub>g</sub> max. (nC)	8.3				
Q <sub>gs</sub> (nC)	2.3				
Q <sub>gd</sub> (nC)	3.8				
Configuration	Single				



#### **FEATURES**

- Dynamic dV/dt rating
- Repetitive avalanche rated
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

#### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF510PbF		
	SiHF510-E3		
SnPb	IRF510		
	SiHF510		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	100		
Gate-Source Voltage			$V_{GS}$	± 20	_ V	
Continuous Drain Current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	1	5.6		
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	4.0	А	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	20		
Linear Derating Factor				0.29	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	75	mJ	
Repetitive Avalanche Current a			I <sub>AR</sub>	5.6	А	
Repetitive Avalanche Energy a			E <sub>AR</sub>	4.3	mJ	
Maximum Power Dissipation $T_C = 25  ^{\circ}C$			$P_{D}$	43	W	
Peak Diode Recovery dV/dt c			dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	00	
Soldering Recommendations (Peak temperature) <sup>d</sup>	for	10 s	-	300	°C	
Mounting Toyour	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b.  $V_{DD}=25$  V, starting  $T_J=25$  °C, L=4.8 mH,  $R_g=25$   $\Omega$ ,  $I_{AS}=5.6$  A (see fig. 12). c.  $I_{SD}\leq5.6$  A,  $dI/dt\leq75$  A/µs,  $V_{DD}\leq V_{DS}$ ,  $T_J\leq175$  °C.

- d. 1.6 mm from case.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62			
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W		
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	3.5			

SPECIFICATIONS (T <sub>J</sub> = 25 °C, t	ınless otherw	ise noted)					
PARAMETER	SYMBOL	TEST (	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$			-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = 1 mA	-	0.12	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V$	<sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	٧
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>G</sub>	V <sub>GS</sub> = ± 20 V		-	± 100	nA
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V		-	-	25	μA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 80 V, V	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	250	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> =3.4 A <sup>b</sup>	-	-	0.54	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 5	0 V, I <sub>D</sub> = 3.4 A <sup>b</sup>	1.3	-	-	S
Dynamic	l	1			1	1	
Input Capacitance	C <sub>iss</sub>	V	<sub>GS</sub> = 0 V,	-	180	-	
Output Capacitance	C <sub>oss</sub>	1 v	os = 25 V,	-	81	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	7	MHz, see fig. 5	-	15	-	, p.
Total Gate Charge	$Q_g$		I <sub>D</sub> = 5.6 A, V <sub>DS</sub> = 80 V	-	-	8.3	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	5   -		-	2.3	nC
Gate-Drain Charge	$Q_{gd}$		see fig. 6 and fig. 13 b	-	-	3.8	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 50 V, $I_{D}$ = 5.6 A $R_{g}$ = 24 $\Omega$ , $R_{D}$ = 8.4 $\Omega$ , see fig. 10 b		-	6.9	-	- ns
Rise Time	t <sub>r</sub>			1	16	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	15	-	
Fall Time	t <sub>f</sub>			1	9.4	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from	_ /_		4.5	-	
Internal Source Inductance	L <sub>S</sub>	package and cer die contact	package and center of		7.5	-	nH
Drain-Source Body Diode Characteristic	cs	1					1
Continuous Source-Drain Diode Current	Is	MOSFET symbo showing the	MOSFET symbol showing the			5.6	_
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	20	A
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub>	$T_J = 25$ °C, $I_S = 5.6$ A, $V_{GS} = 0$ V b		-	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 5.6 A, dI/dt = 100 A/µs b		-	100	200	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	0.44	0.88	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L <sub>D</sub> )				L <sub>D</sub> )	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

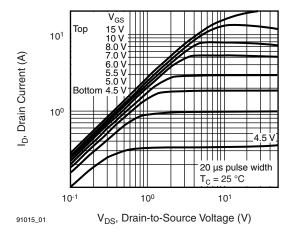


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

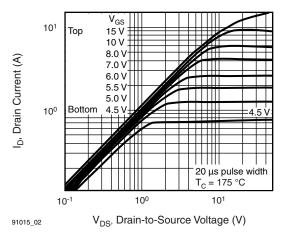


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

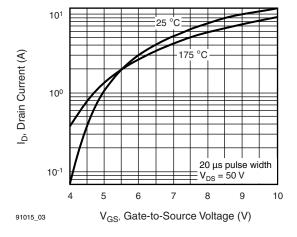


Fig. 3 - Typical Transfer Characteristics

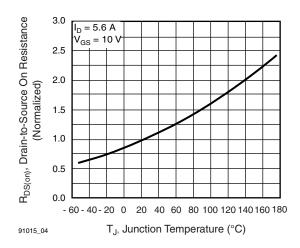


Fig. 4 - Normalized On-Resistance vs. Temperature

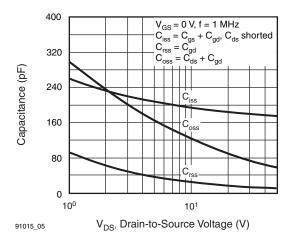


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

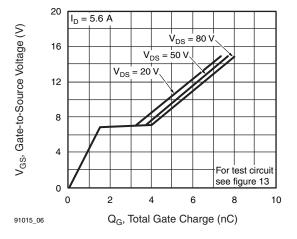


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



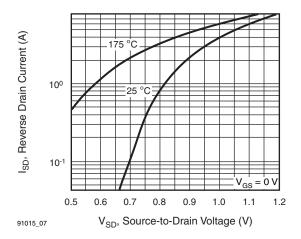


Fig. 7 - Typical Source-Drain Diode Forward Voltage

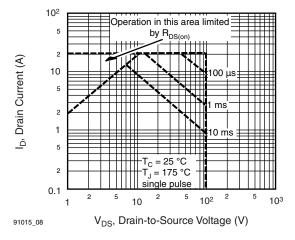


Fig. 8 - Maximum Safe Operating Area

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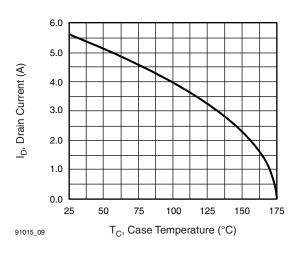


Fig. 9 - Maximum Drain Current vs. Case Temperature

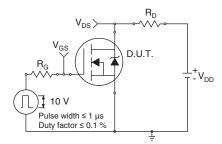


Fig. 10a - Switching Time Test Circuit

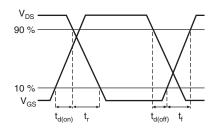


Fig. 10b - Switching Time Waveforms

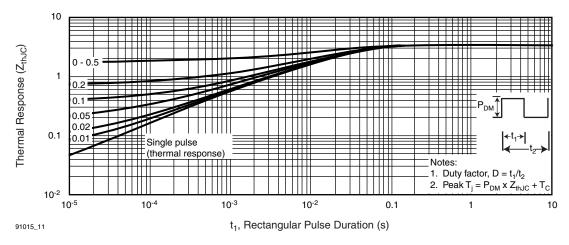


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



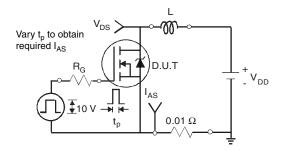


Fig. 12a - Unclamped Inductive Test Circuit

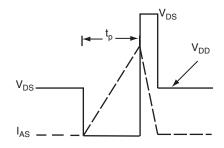


Fig. 12b - Unclamped Inductive Waveforms

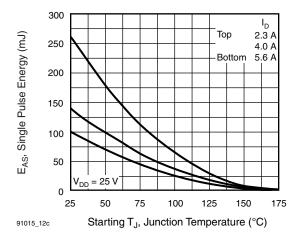


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

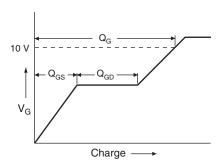


Fig. 13a - Basic Gate Charge Waveform

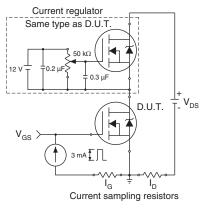
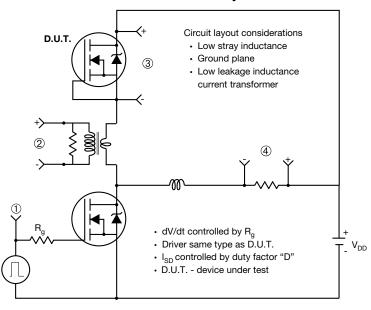


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



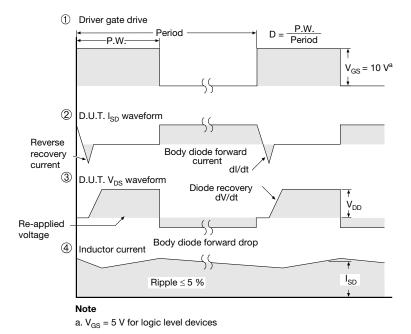


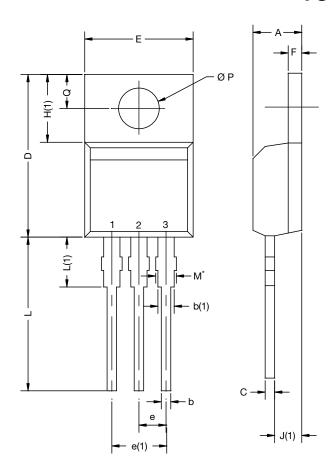
Fig. 14 - For N-Channel

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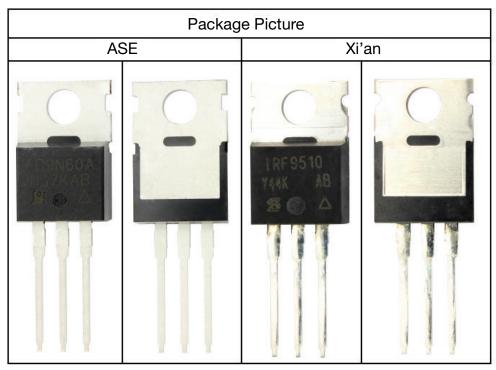
# TO-220-1



DIM	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
E	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031						

#### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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